

650V CoolMOS™ E6 Power Transistor

IPA65R190E6, IPB65R190E6
IPI65R190E6, IPP65R190E6
IPW65R190E6

1 Description

CoolMOS™ is a revolutionary technology for high voltage power MOSFETs, designed according to the superjunction (SJ) principle and pioneered by Infineon Technologies. CoolMOS™ E6 series combines the experience of the leading SJ MOSFET supplier with high class innovation. The offered devices provide all benefits of a fast switching SJ MOSFET while not sacrificing ease of use. Extremely low switching and conduction losses make switching applications even more efficient, more compact, lighter, and cooler.

Features

- Extremely low losses due to very low FOM $R_{\text{DS(on)}} \cdot Q_g$ and E_{oss}
- Very high commutation ruggedness
- Easy to use/drive
- JEDEC¹⁾ qualified, Pb-free plating, Halogen free

Applications

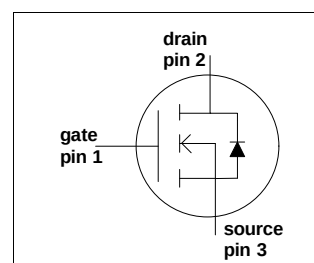
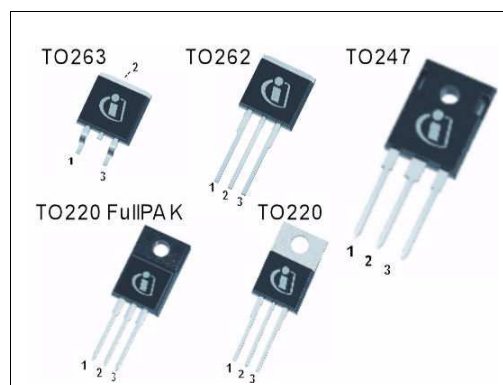
PFC stages, hard switching PWM stages and resonant switching PWM stages for e.g. PC Silverbox, Adapter, LCD & PDP TV, Lighting, Server, Telecom and UPS.

Please note: For MOSFET paralleling the use of ferrite beads on the gate or separate totem poles is generally recommended.

Table 1 Key Performance Parameters

Parameter	Value	Unit
$V_{\text{DS}} @ T_{\text{j,max}}$	700	V
$R_{\text{DS(on),max}}$	0.19	Ω
$Q_{\text{g,typ}}$	73	nC
$I_{\text{D,pulse}}$	66	A
$E_{\text{oss}} @ 400\text{V}$	5.9	μJ
Body diode di/dt	500	A/ μs

Type / Ordering Code	Package	Marking	Related Links
IPW65R190E6	PG-TO247	65E6190	IFX CoolMOS Webpage IFX Design tools
IPB65R190E6	PG-TO263		
IPI65R190E6	PG-TO262		
IPP65R190E6	PG-TO220		
IPA65R190E6	PG-TO220 FullPAK		



1) J-STD20 and JESD22

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2 Maximum ratings

at $T_j = 25\text{ °C}$, unless otherwise specified.

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D	-	-	20.2	A	$T_C = 25\text{ °C}$
				12.8		$T_C = 100\text{ °C}$
Pulsed drain current ²⁾	$I_{D,pulse}$	-	-	66	A	$T_C = 25\text{ °C}$
Avalanche energy, single pulse	E_{AS}	-	-	485	mJ	$I_D = 3.5\text{ A}, V_{DD} = 50\text{ V}$
Avalanche energy, repetitive	E_{AR}	-	-	0.73		$I_D = 3.5\text{ A}, V_{DD} = 50\text{ V}$
Avalanche current, repetitive	I_{AR}	-	-	3.5	A	
MOSFET dv/dt ruggedness	dv/dt	-	-	50	V/ns	$V_{DS} = 0 \dots 480\text{ V}$
Gate source voltage	V_{GS}	-20	-	20	V	static
		-30		30		AC ($f > 1\text{ Hz}$)
Power dissipation for TO-220, TO-247, TO-262, TO-263	P_{tot}	-	-	151	W	$T_C = 25\text{ °C}$
Power dissipation for TO-220 FullPAK	P_{tot}	-	-	34		
Operating and storage temperature	T_j, T_{stg}	-55	-	150	°C	
Mounting torque TO-220, TO-247		-	-	60	Ncm	M3 and M3.5 screws
Mounting torque TO-220 FullPAK				50		M2.5 screws
Continuous diode forward current	I_S	-	-	17.5	A	$T_C = 25\text{ °C}$
Diode pulse current ²⁾	$I_{S,pulse}$	-	-	66	A	$T_C = 25\text{ °C}$
Reverse diode dv/dt ³⁾	dv/dt	-	-	15	V/ns	$V_{DS} = 0 \dots 400\text{ V}, I_{SD} \leq I_D, T_j = 25\text{ °C}$
Maximum diode commutation speed ³⁾	di/dt			500	A/μs	

1) Limited by $T_{j,max}$. Maximum duty cycle $D=0.75$

2) Pulse width t_p limited by $T_{j,max}$

3) Identical low side and high side switch with identical R_G

3 Thermal characteristics

Table 3 Thermal characteristics non FullPAK

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.83	°C/W	leded
Thermal resistance, junction - ambient	R_{thJA}	-	-	62		
Soldering temperature, wavesoldering only allowed at leads	T_{sold}	-	-	260	°C	1.6 mm (0.063 in.) from case for 10 s

Table 4 Thermal characteristics FullPAK

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	3.7	°C/W	leded
Thermal resistance, junction - ambient	R_{thJA}	-	-	80		
Soldering temperature, wavesoldering only allowed at leads	T_{sold}	-	-	260	°C	1.6 mm (0.063 in.) from case for 10 s

Table 5 Thermal characteristics SMD

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.83	°C/W	SMD version, device on PCB, minimal footprint
Thermal resistance, junction - ambient	R_{thJA}	-	-	62		
		-	35	-		
Soldering temperature, wave- & reflow soldering allowed	T_{sold}	-	-	260	°C	reflow MSL1

1) Device on 40mm*40mm*1.5mm one layer epoxy PCB FR4 with 6cm² copper area (thickness 70µm) for drain connection. PCB is vertical without air stream cooling.

4 Electrical characteristics

Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified.

Table 6 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	650	-	-	V	$V_{GS}=0\text{ V}$, $I_D=1.0\text{ mA}$
Gate threshold voltage	$V_{GS(th)}$	2.5	3	3.5		$V_{DS}=V_{GS}$, $I_D=0.73\text{ mA}$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=650\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$
		-	10	-		$V_{DS}=650\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=150\text{ °C}$
Gate-source leakage current	I_{GSS}	-	-	100	nA	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	0.17	0.19	Ω	$V_{GS}=10\text{ V}$, $I_D=7.3\text{ A}$, $T_j=25\text{ °C}$
		-	0.44	-		$V_{GS}=10\text{ V}$, $I_D=7.3\text{ A}$, $T_j=150\text{ °C}$
Gate resistance	R_G	-	6	-	Ω	$f=1\text{ MHz}$, open drain

Table 7 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	1620	-	pF	$V_{GS}=0\text{ V}$, $V_{DS}=100\text{ V}$, $f=1\text{ MHz}$
Output capacitance	C_{oss}	-	98	-		
Effective output capacitance, energy related ¹⁾	$C_{o(er)}$	-	65	-		$V_{GS}=0\text{ V}$, $V_{DS}=0\ldots 480\text{ V}$
Effective output capacitance, time related ²⁾	$C_{o(tr)}$	-	308	-		$I_D=\text{constant}$, $V_{GS}=0\text{ V}$ $V_{DS}=0\ldots 480\text{ V}$
Turn-on delay time	$t_{d(on)}$	-	12	-	ns	$V_{DD}=400\text{ V}$, $V_{GS}=13\text{ V}$, $I_D=11\text{ A}$, $R_G=3.4\text{ }\Omega$
Rise time	t_r	-	11	-		
Turn-off delay time	$t_{d(off)}$	-	112	-		
Fall time	t_f	-	10	-		

1) $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$

2) $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$

Table 8 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	8.9	-	nC	$V_{DD}=480\text{ V}$, $I_D=11\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate to drain charge	Q_{gd}	-	38	-		
Gate charge total	Q_g	-	73	-		
Gate plateau voltage	V_{plateau}	-	5.5	-	V	

Table 9 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.9	-	V	$V_{GS}=0\text{ V}$, $I_F=11\text{ A}$, $T_j=25\text{ °C}$
Reverse recovery time	t_{rr}	-	410	-	ns	$V_R=400\text{ V}$, $I_F=11\text{ A}$, $di_F/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}	-	6.1	-	μC	
Peak reverse recovery current	I_{rrm}	-	28	-	A	

5 Electrical characteristics diagrams

Table 10

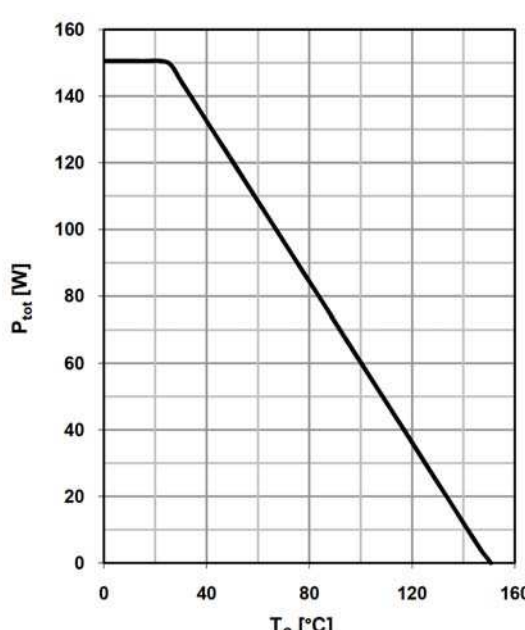
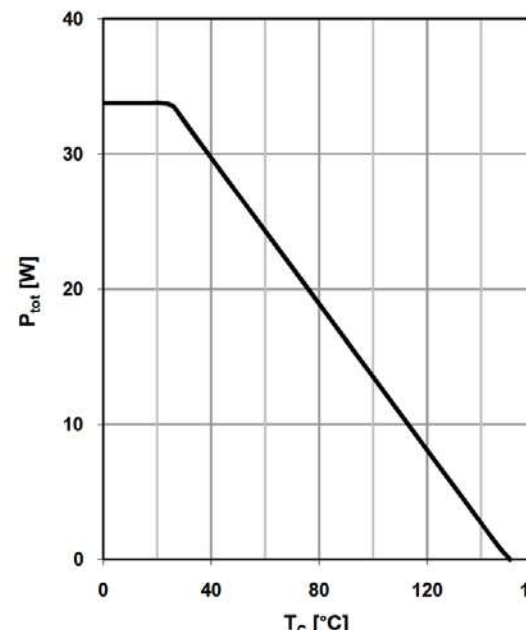
Power dissipation Non FullPAK	Power dissipation FullPAK
	
$P_{tot} = f(T_c)$	$P_{tot} = f(T_c)$

Table 11

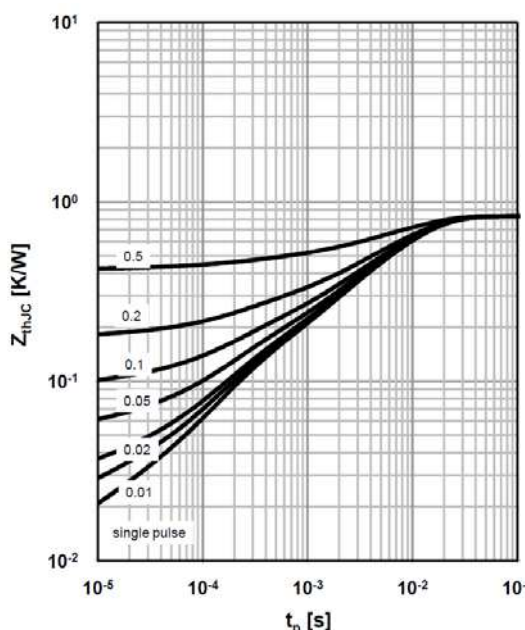
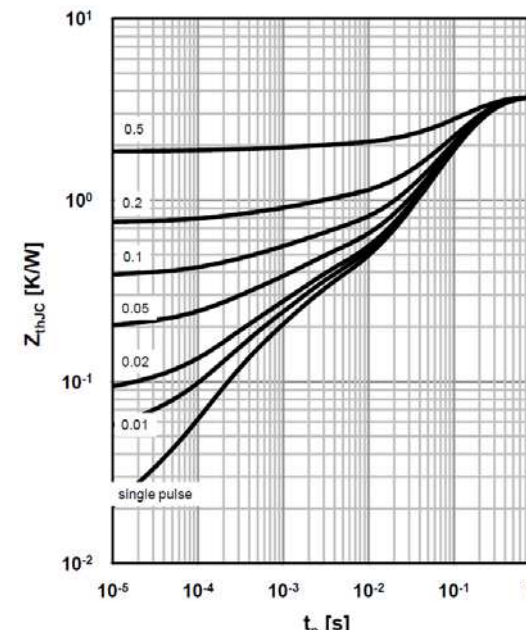
Max. transient thermal impedance Non FullPAK	Max. transient thermal impedance FullPAK
	
$Z_{(thJC)} = f(t_p)$; parameter: $D = t_p / T$	$Z_{(thJC)} = f(t_p)$; parameter: $D = t_p / T$

Table 12

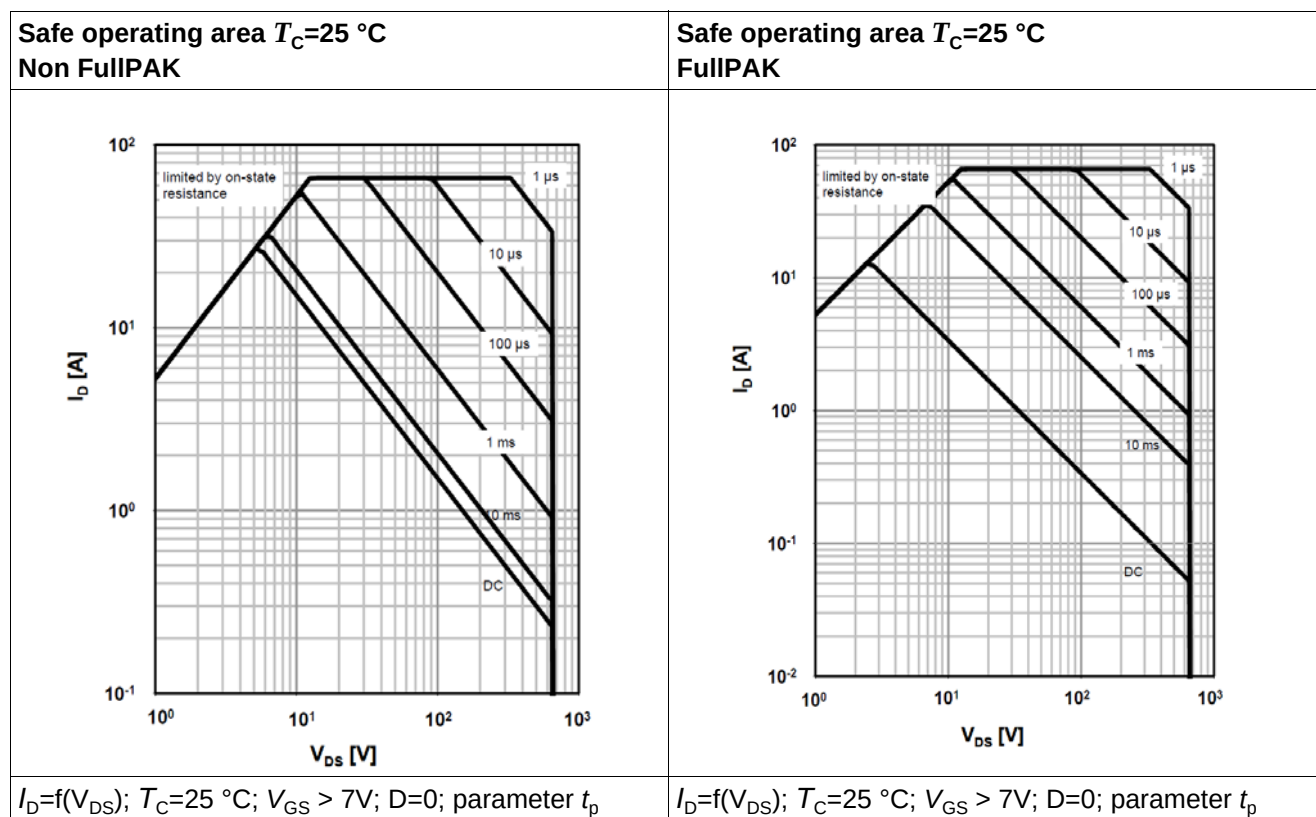


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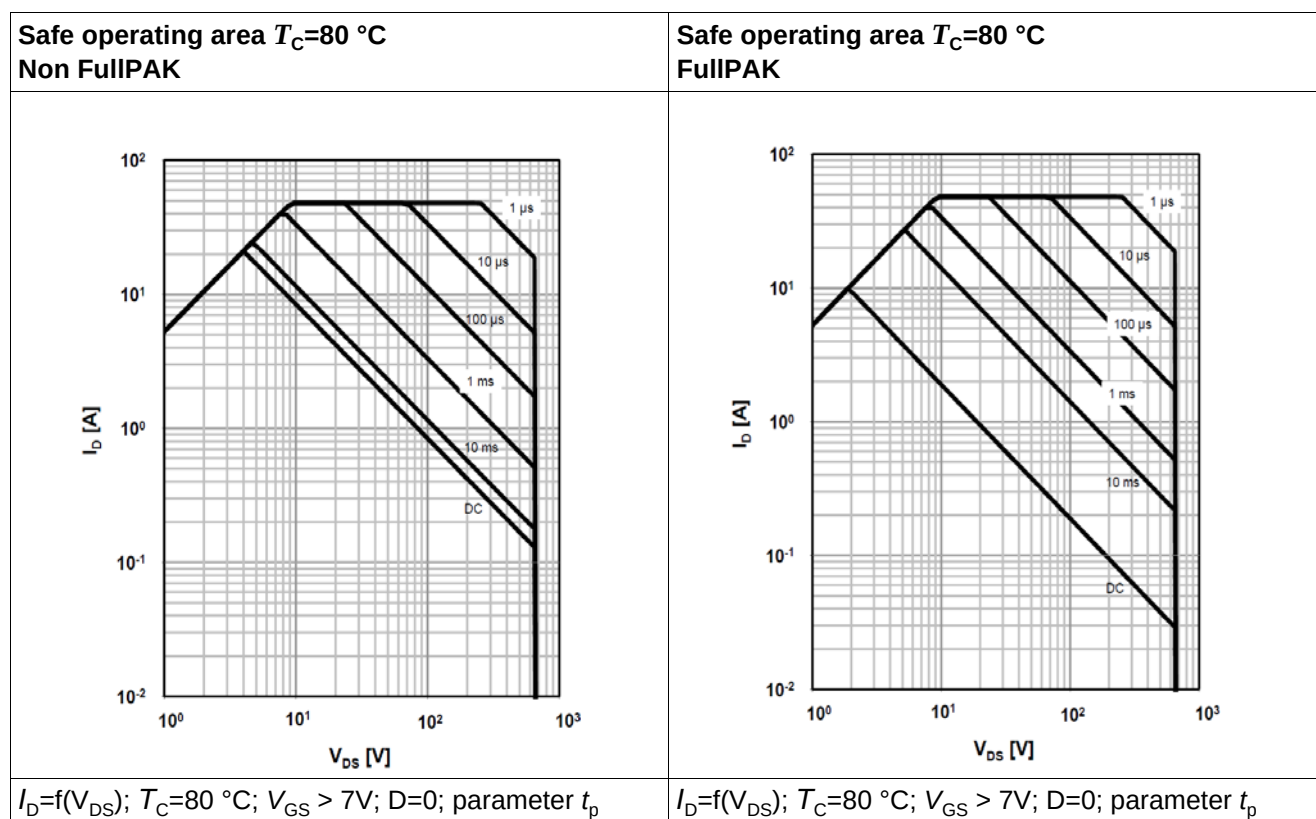


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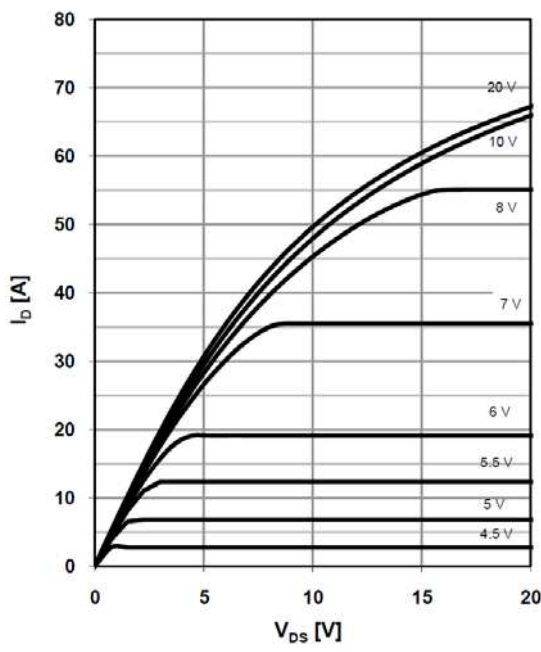
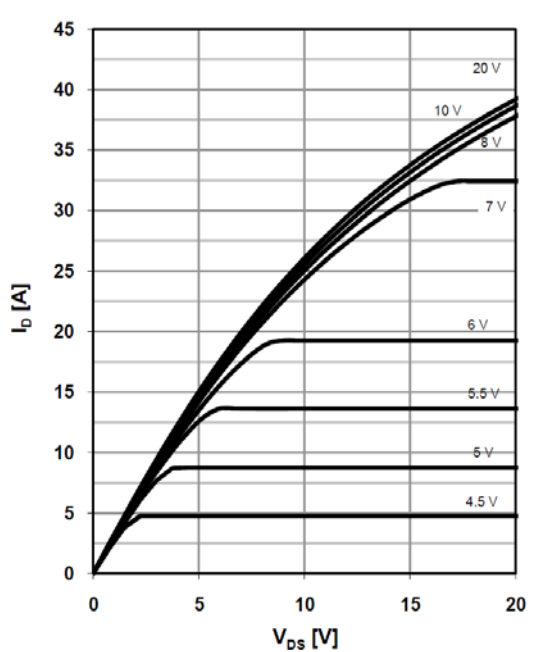
Typ. output characteristics $T_J=25\text{ °C}$	Typ. output characteristics $T_J=125\text{ °C}$
	
$I_D=f(V_{DS}); T_J=25\text{ °C}; \text{parameter: } V_{GS}$	$I_D=f(V_{DS}); T_J=125\text{ °C}; \text{parameter: } V_{GS}$

Table 15

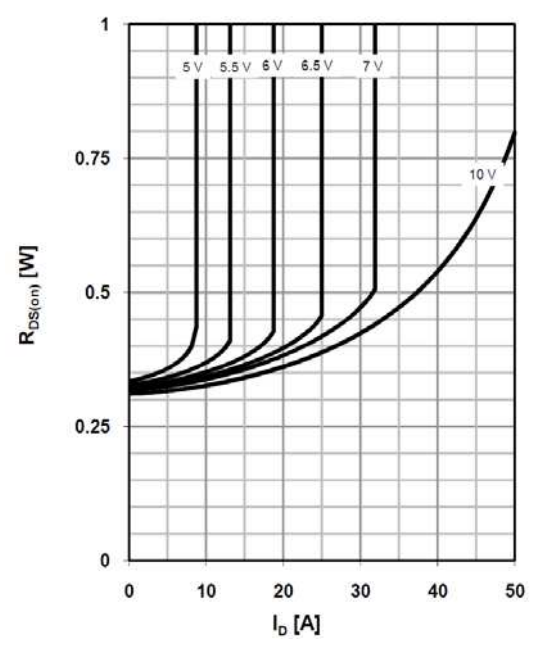
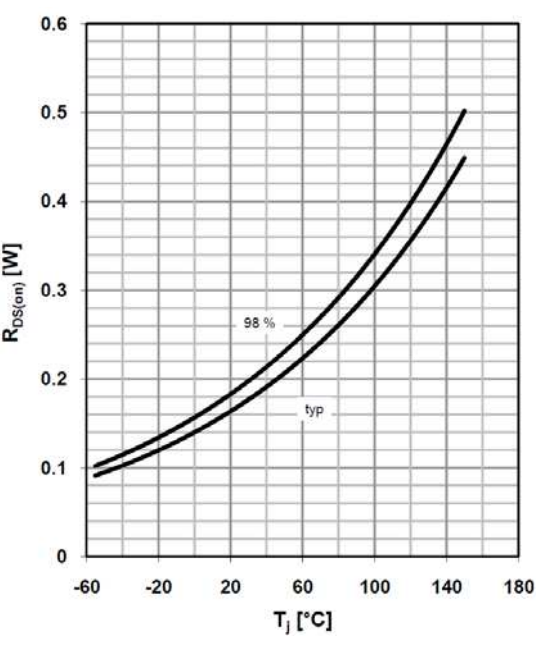
Typ. drain-source on-state resistance	Drain-source on-state resistance
	
$R_{DS(on)}=f(I_D); T_J=125\text{ °C}; \text{parameter: } V_{GS}$	$R_{DS(on)}=f(T_J); I_D=7.3\text{ A}; V_{GS}=10\text{ V}$

Table 16

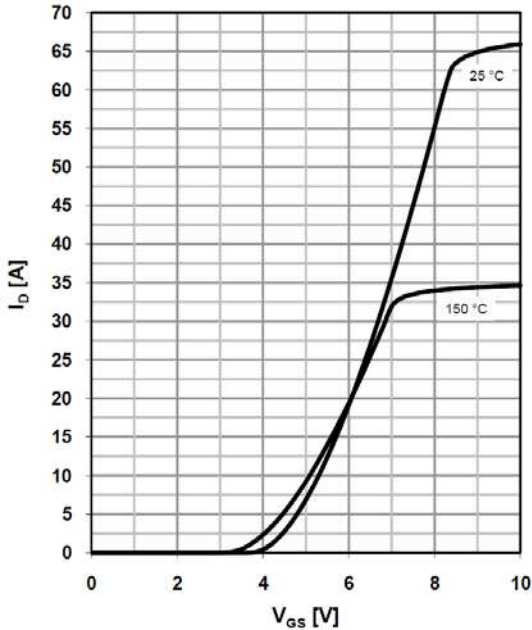
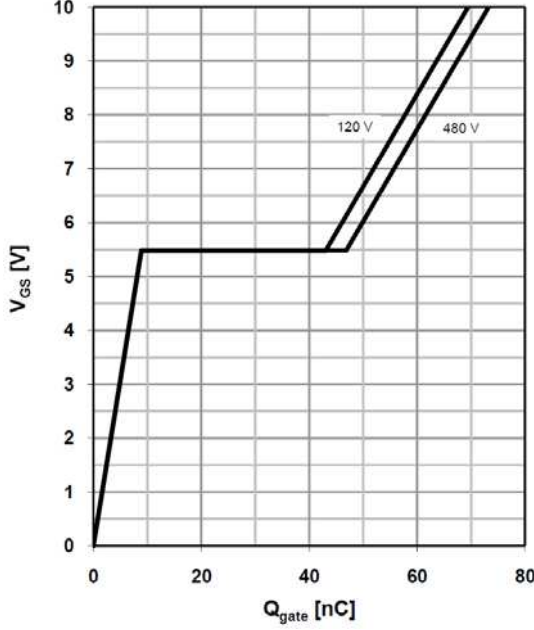
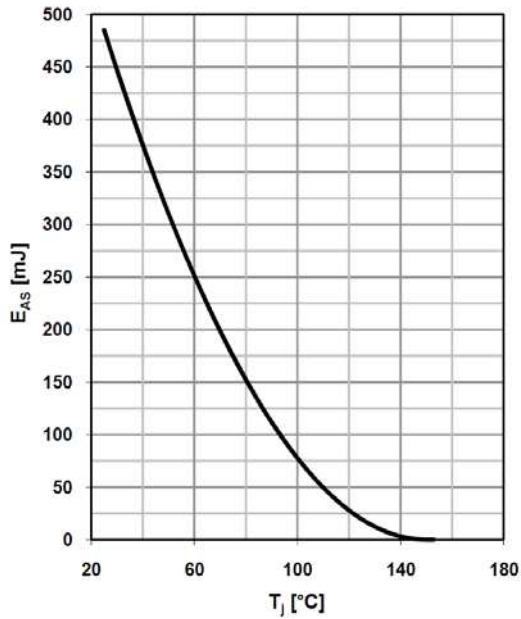
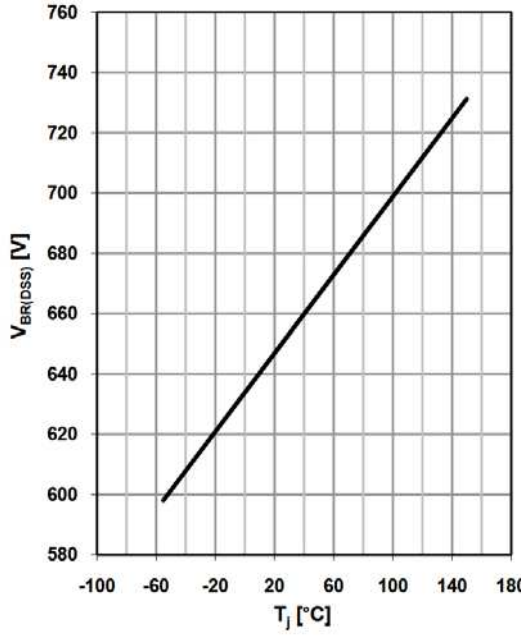
Typ. transfer characteristics	Typ. gate charge
 $I_D = f(V_{GS}); V_{DS} = 20V$	 $V_{GS} = f(Q_{gate}), I_D = 11 \text{ A pulsed}$

Table 17

Avalanche energy	Drain-source breakdown voltage
 $E_{AS} = f(T_j); I_D = 3.5 \text{ A}; V_{DD} = 50 \text{ V}$	 $V_{BR(DSS)} = f(T_j); I_D = 1.0 \text{ mA}$

Electrical characteristics diagrams

Table 18

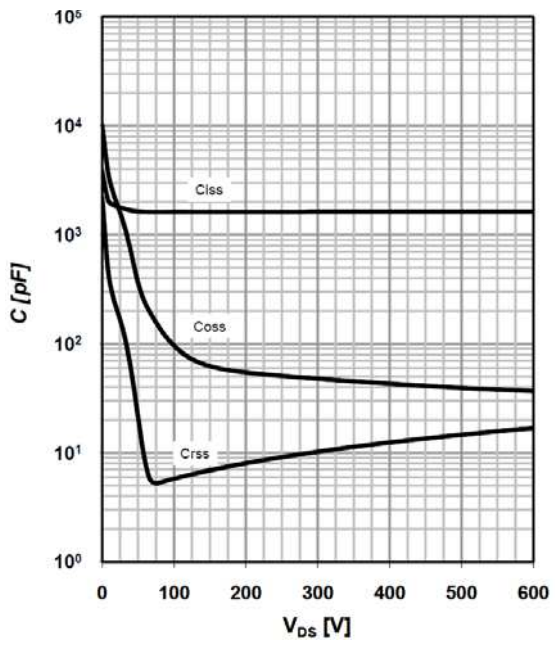
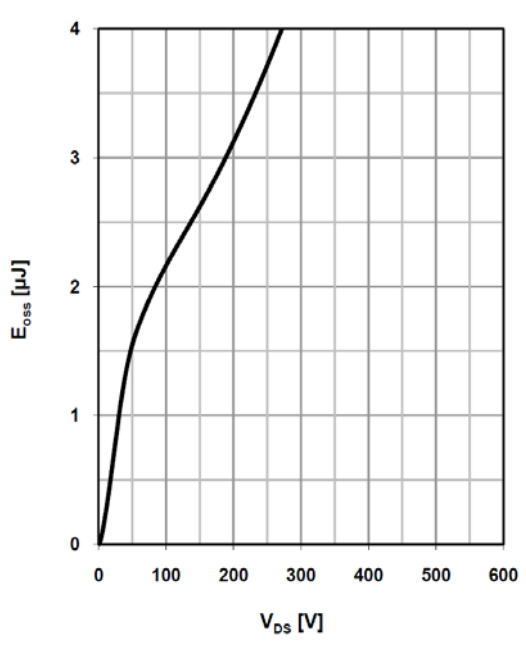
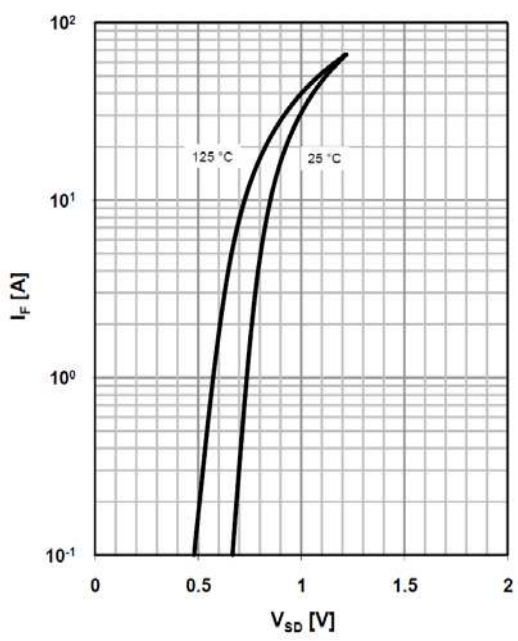
Typ. capacitances	Typ. C_{oss} stored energy
	
$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}$	$E_{oss}=f(V_{DS})$

Table 19

Forward characteristics of reverse diode

$I_F=f(V_{SD}); \text{parameter: } T_j$

6 Test circuits

Table 20 Switching times test circuit and waveform for inductive load

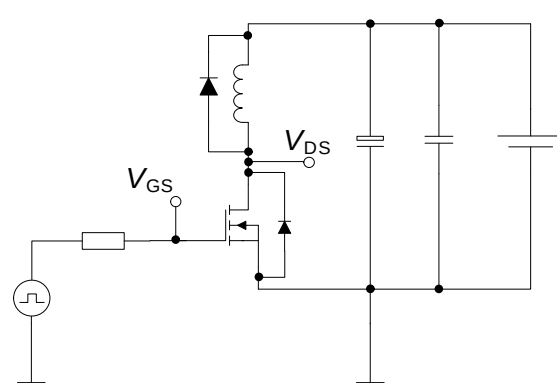
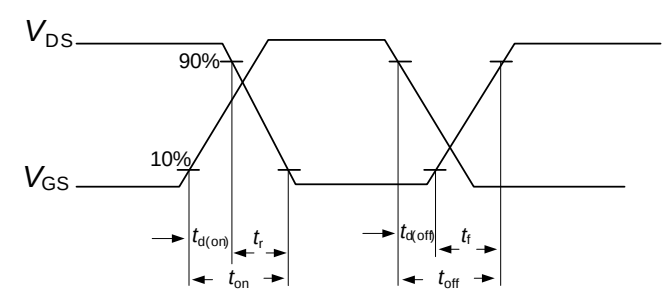
Switching times test circuit for inductive load	Switching time waveform
	

Table 21 Unclamped inductive load test circuit and waveform

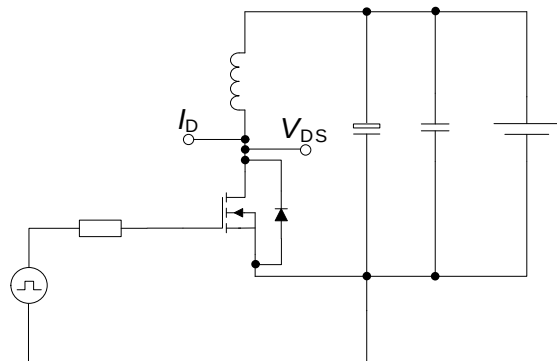
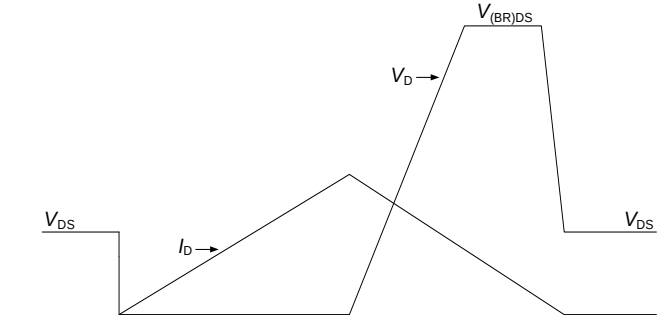
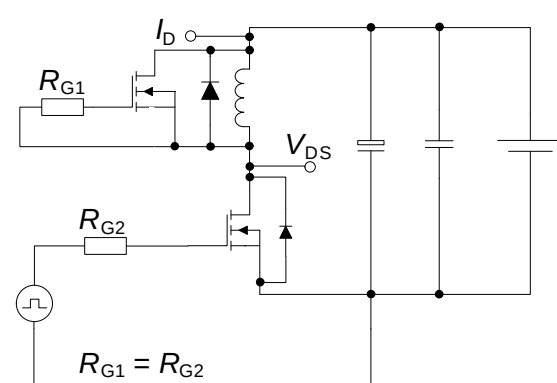
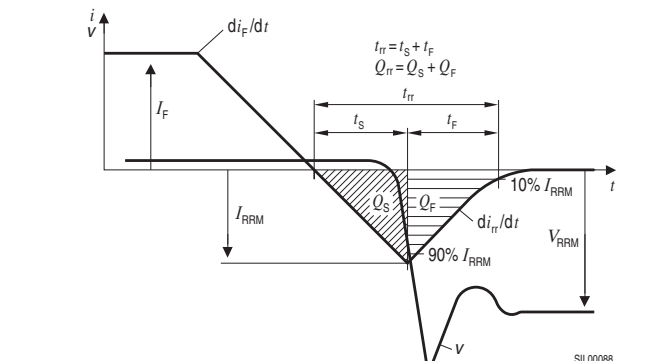
Unclamped inductive load test circuit	Unclamped inductive waveform
	

Table 22 Test circuit and waveform for diode characteristics

Test circuit for diode characteristics	Diode recovery waveform
 $R_{G1} = R_{G2}$	 i v di_F/dt I_F I_{RRM} V_{RRM} $10\% I_{RRM}$ $90\% I_{RRM}$ di_n/dt t_s t_r t_f $t_n = t_s + t_f$ $Q_n = Q_s + Q_f$ Q_s Q_f $SIL00088$

7 Package outlines

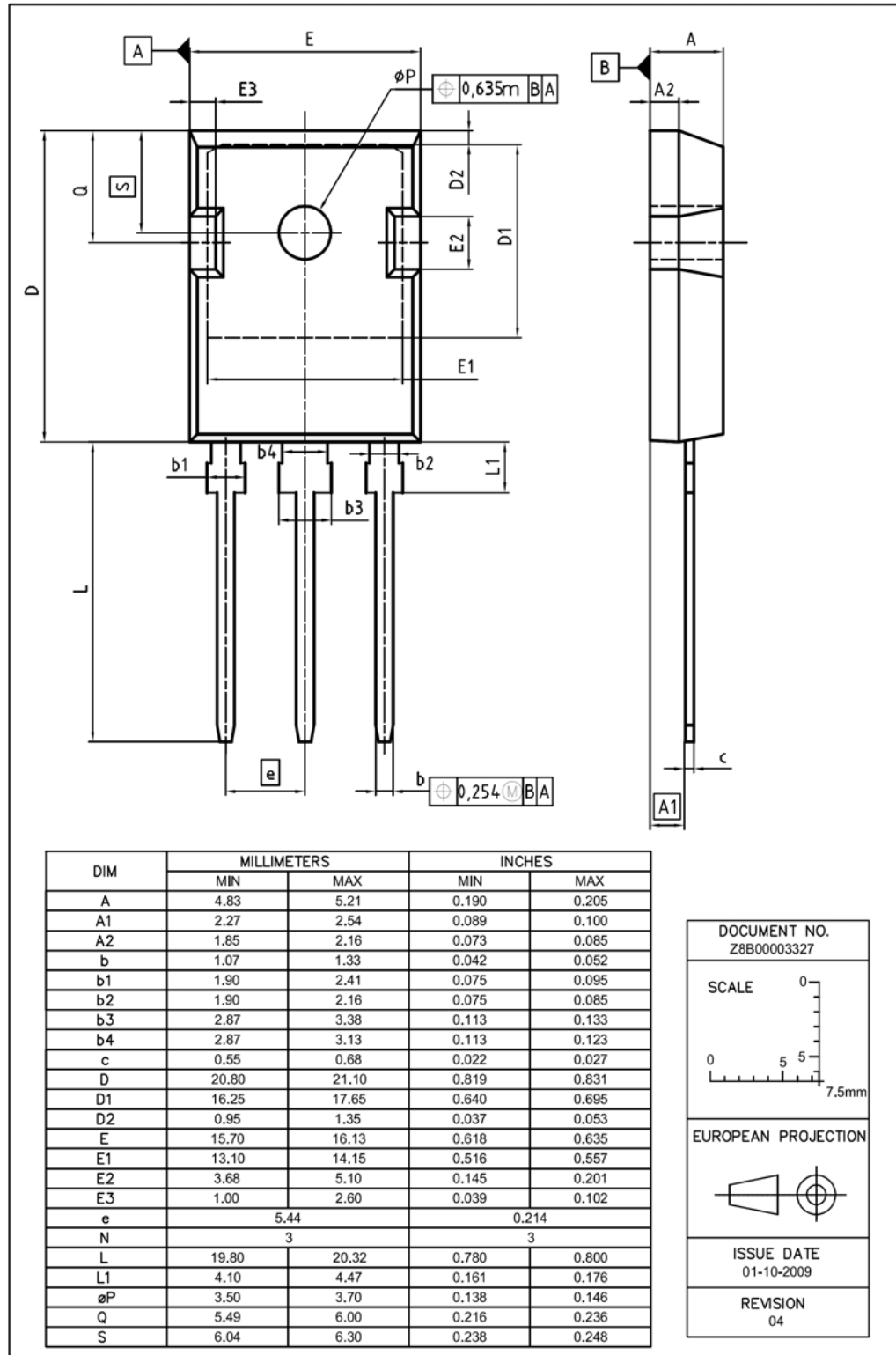
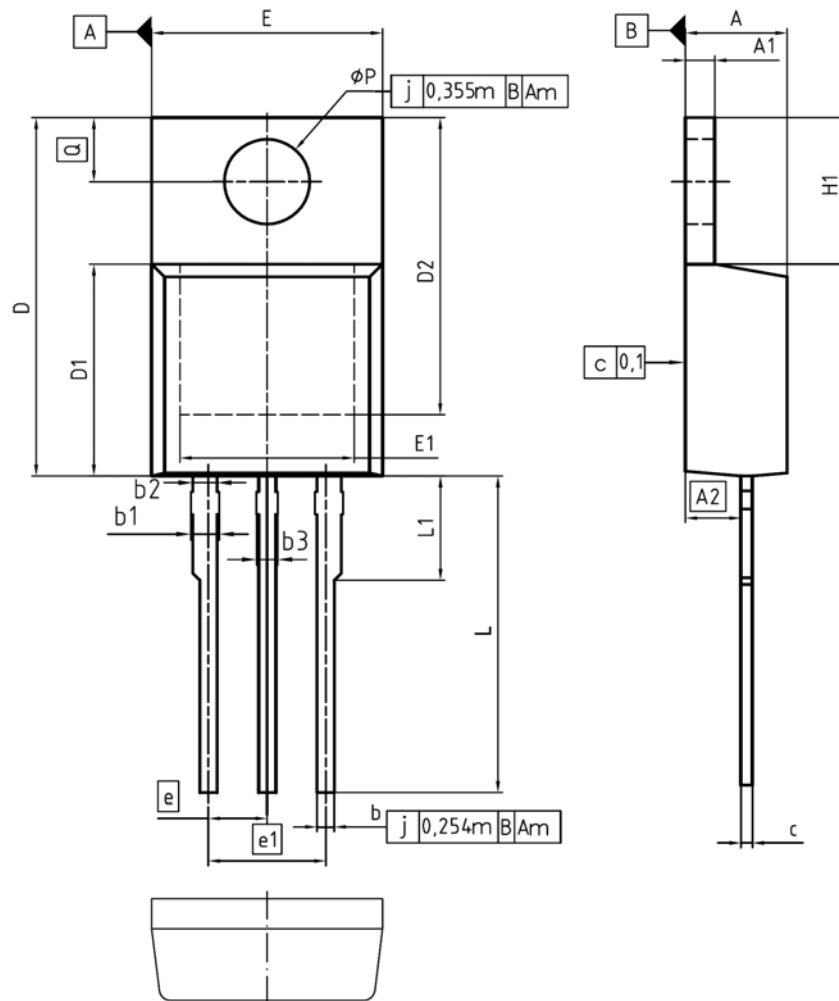


Figure 1 Outlines TO-247, dimensions in mm/inches



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	1.17	1.40	0.046	0.055
A2	2.15	2.72	0.085	0.107
b	0.65	0.86	0.026	0.034
b1	0.95	1.40	0.037	0.055
b2	0.95	1.15	0.037	0.045
b3	0.65	1.15	0.026	0.045
c	0.33	0.60	0.013	0.024
D	14.81	15.95	0.583	0.628
D1	8.51	9.45	0.335	0.372
D2	12.19	13.10	0.480	0.516
E	9.70	10.36	0.382	0.408
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H1	5.90	6.90	0.232	0.272
L	13.00	14.00	0.512	0.551
L1	-	4.80	-	0.189
phi P	3.60	3.89	0.142	0.153
Q	2.60	3.00	0.102	0.118

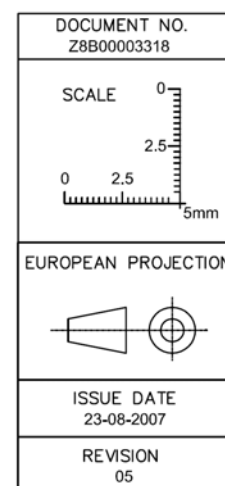


Figure 2 Outlines TO-220, dimensions in mm/inches

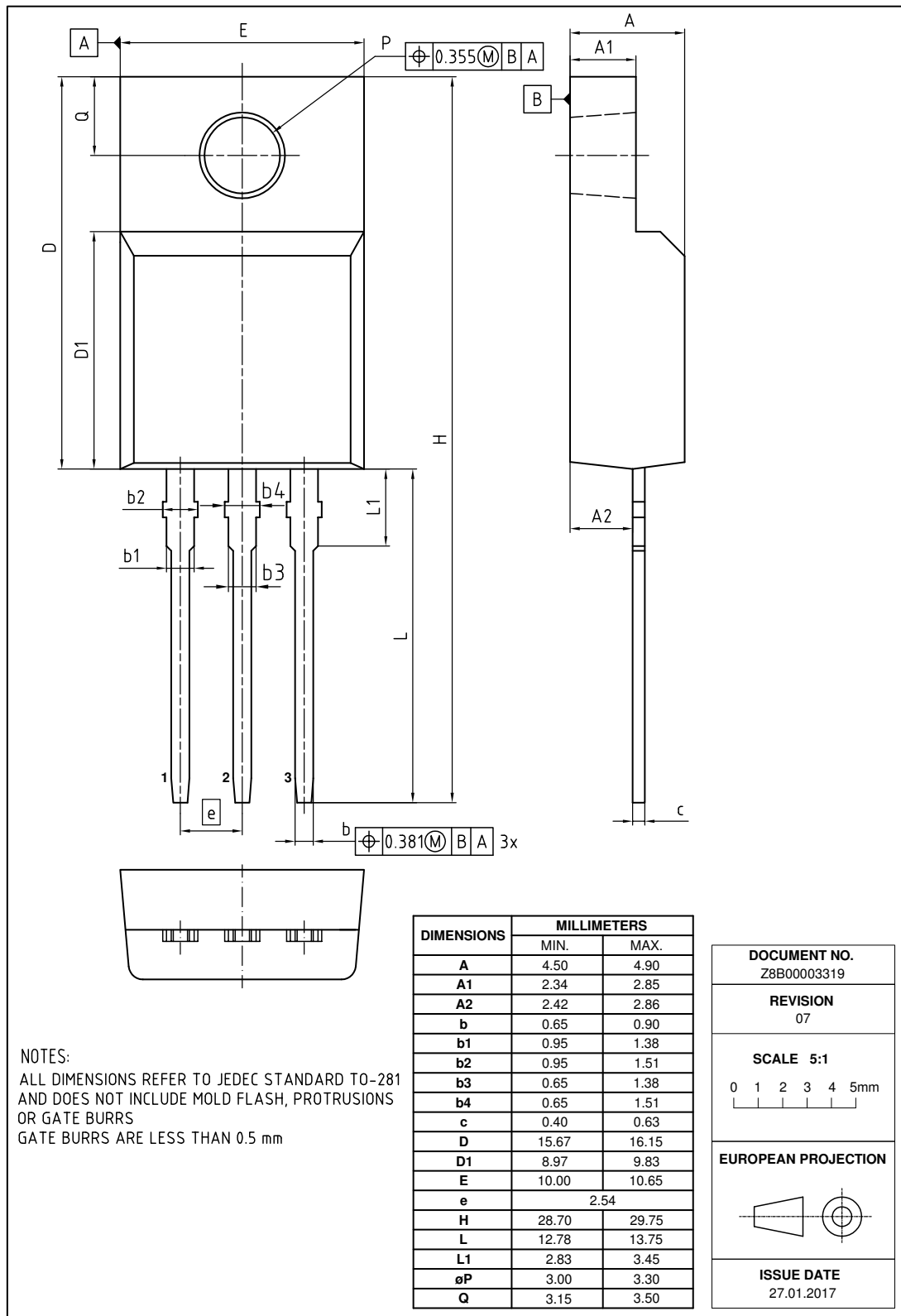
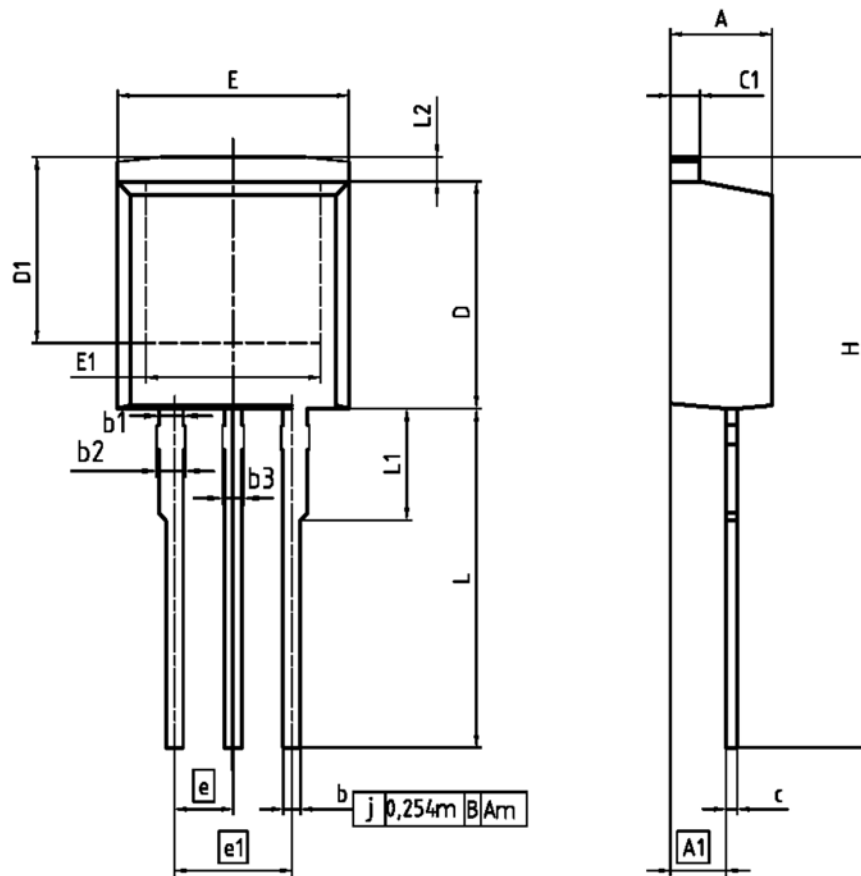


Figure 3 Outlines TO-220 FullPAK, dimensions in mm



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.300	4.572	0.169	0.180
A1	2.150	2.718	0.085	0.107
b	0.650	0.864	0.026	0.034
b1	0.950	1.093	0.037	0.043
b2	0.950	1.400	0.037	0.055
b3	0.850	1.118	0.026	0.044
c	0.330	0.600	0.013	0.024
c1	1.170	1.400	0.046	0.055
D	8.509	9.450	0.335	0.372
D1	6.900	-	0.272	-
E	9.700	10.363	0.382	0.408
E1	6.500	8.600	0.256	0.339
e	2.540		0.100	
e1	5.080		0.200	
N	3		3	
L	13.000	14.000	0.512	0.551
L1	-	4.800	-	0.189
L2	-	1.727	-	0.068

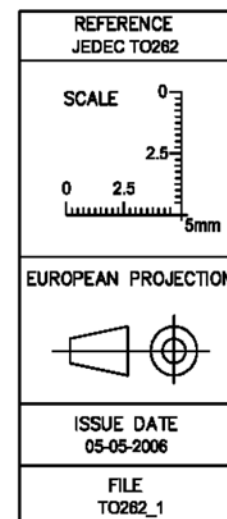


Figure 4 Outlines TO-262, dimensions in mm/inches

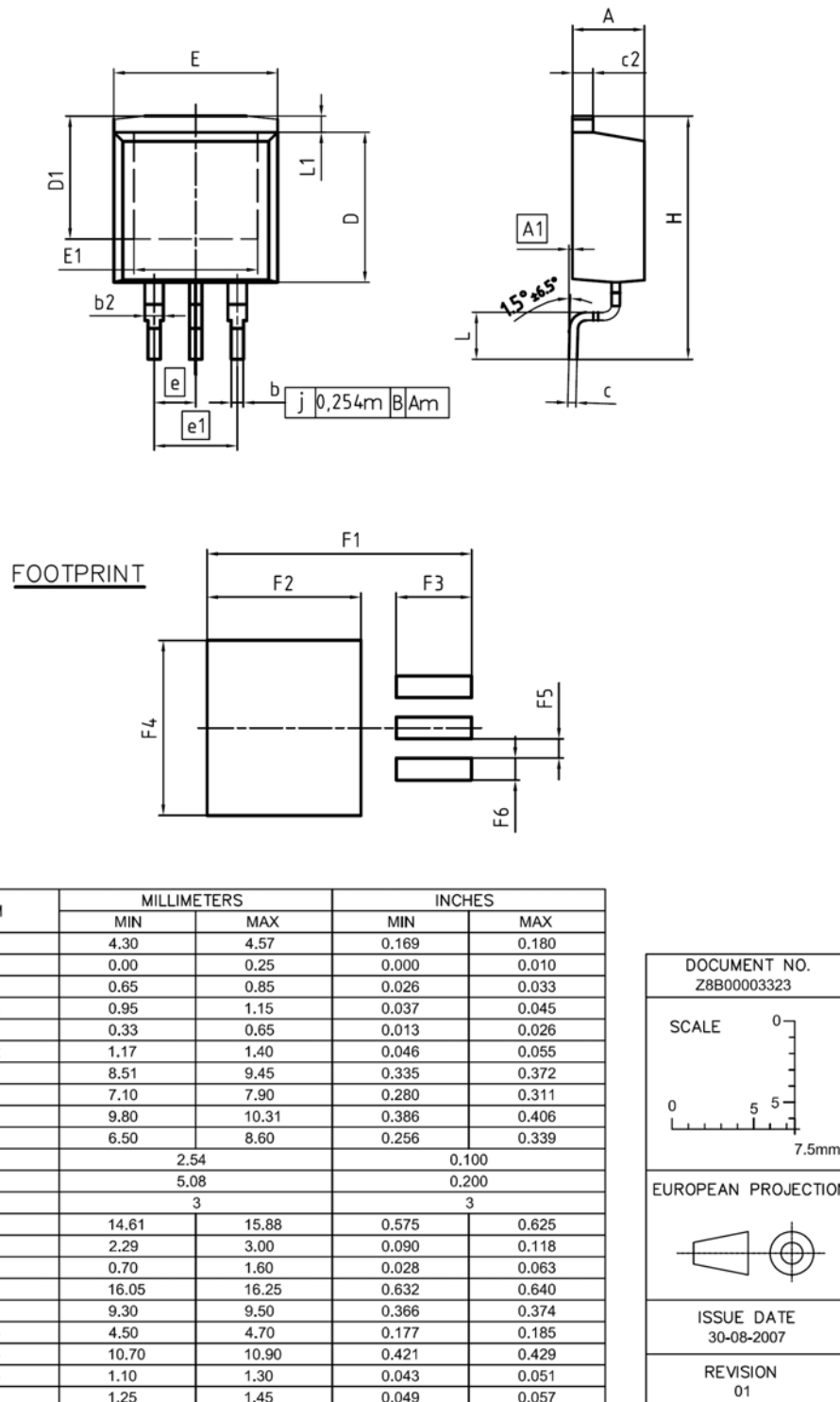


Figure 5 Outlines TO-263, dimensions in mm/inches

Revision History

IPx65R190E6

Revision: 2018-03-05, Rev. 2.1

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.1	2018-03-05	Outline PG-TO-220 FullPAK update

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Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

The Infineon Technologies component described in this Data Sheet may be used in life-support devices or systems and/or automotive, aviation and aerospace applications or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support, automotive, aviation and aerospace device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.